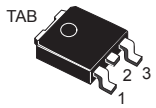
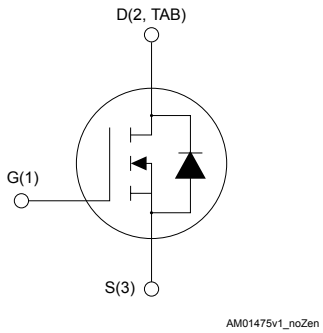
Automotive-grade N-channel 250 V, 318 mΩ typ., 8 A, STripFET II Power MOSFET in a DPAK package



DPAK



Features

Order code	V_{DS}	$R_{DS(on)}$max.	I_D
STD8NF25	250 V	420 mΩ	8 A

- AEC-Q101 qualified
- 100% avalanche tested
- 175 °C maximum junction temperature

Applications

- Switching applications

Description

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

Product status link
STD8NF25

Product summary	
Order code	STD8NF25
Marking	8NF25
Package	DPAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	250	V
V_{GS}	Gate-source voltage	±20	V
I_D	Drain current (continuous) at T_C = 25 °C	8	A
	Drain current (continuous) at T_C = 100 °C	6	A
I_{DM}(1)	Drain current (pulsed)	32	A
P_{TOT}	Total power dissipation at T_C = 25 °C	72	W
T_J	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		

1. *Pulse width is limited by safe operating area.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	2.08	°C/W
R_{thJA}(1)	Thermal resistance, junction-to-ambient	50	°C/W

1. *When mounted on an 1-inch² FR-4, 2 Oz copper board*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or non-repetitive (pulse width limited by T_{jmax})	8	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	110	mJ

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	250			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 250 V			1	µA
		V_{GS} = 0 V, V_{DS} = 250 V, T_C = 125 °C (1)			50	µA
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 8 A		318	420	mΩ

1. *specified by design, not tested in production.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	500	-	pF
C_{oss}	Output capacitance		-	90	-	
C_{rss}	Reverse transfer capacitance		-	15	-	
Q_g	Total gate charge	V_{DD} = 200 V, I_D = 8 A, V_{GS} = 0 to 10 V (see Figure 13. Test circuit for gate charge behavior)	-	16	-	nC
Q_{gs}	Gate-source charge			3.5	-	
Q_{gd}	Gate-drain charge			8		

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 125 V, I_D = 4 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	13	-	ns
t_r	Rise time		-	10	-	
$t_{d(off)}$	Turn-off delay time		-	26	-	
t_f	Fall time		-	6	-	

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		8	A
I_{SDM}(1)	Source-drain current (pulsed)		-	-	32	
V_{SD}(2)	Forward on voltage	I_{SD} = 8 A, V_{GS} = 0 V	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 8 A, di/dt = 100 A/µs, V_{DD} = 50 V (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	115	-	ns
Q_{rr}	Reverse recovery charge		-	0.47	-	µC
I_{RRM}	Reverse recovery current		-	8.5	-	A
t_{rr}	Reverse recovery time	I_{SD} = 8 A, di/dt = 100 A/µs, V_{DD} = 50 V, T_j = 150 °C (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	130		ns
Q_{rr}	Reverse recovery charge		-	0.58	-	µC
I_{RRM}	Reverse recovery current		-	9.5	-	A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

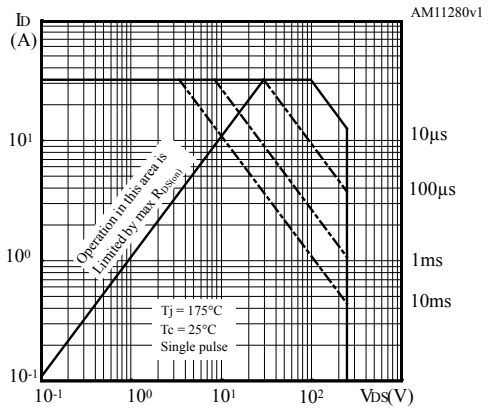


Figure 2. Thermal impedance

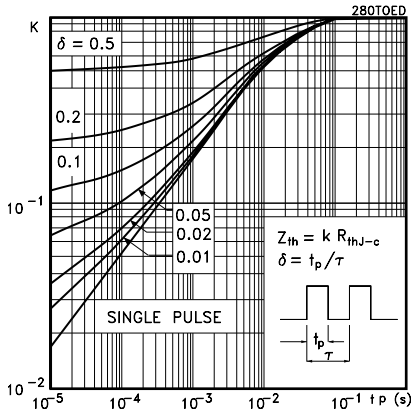


Figure 3. Output characteristics

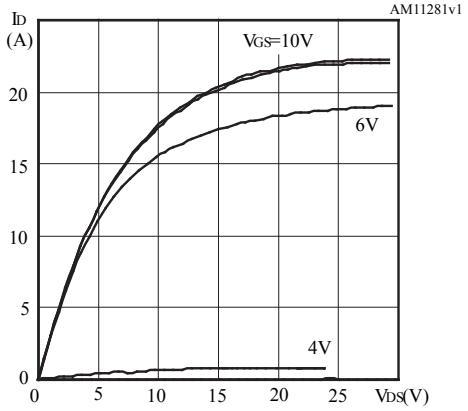


Figure 4. Transfer characteristics

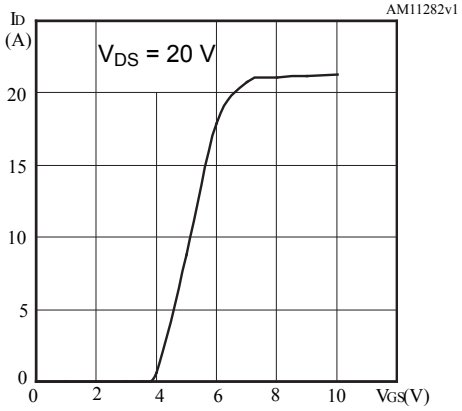


Figure 5. Normalized $V_{(BR)DSS}$ vs temperature

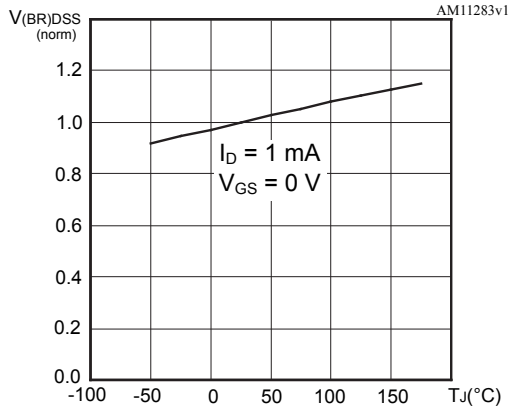


Figure 6. Static drain-source on-resistance

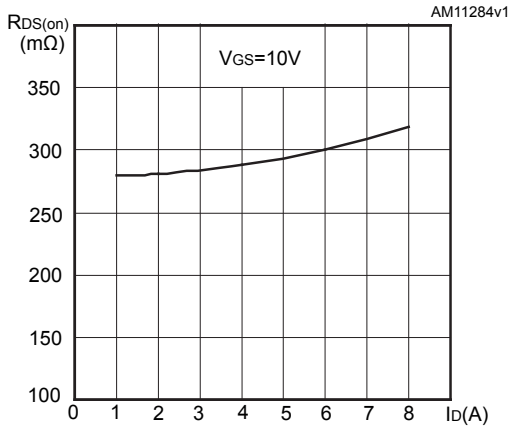


Figure 7. Gate charge vs gate-source voltage

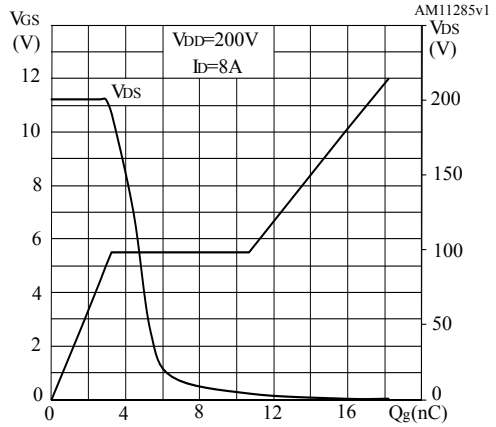


Figure 8. Capacitance variations

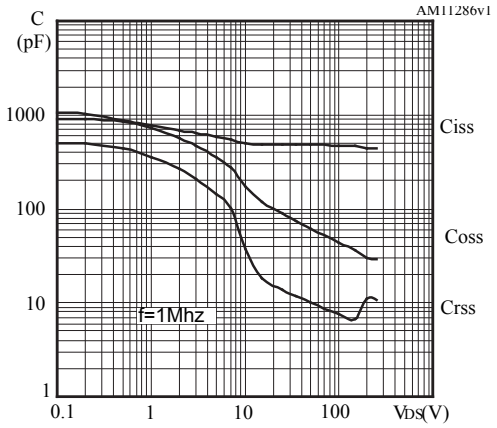


Figure 9. Normalized gate threshold voltage vs temperature

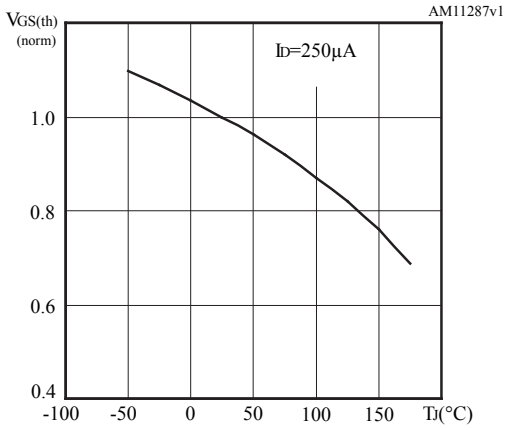


Figure 10. Normalized on-resistance vs temperature

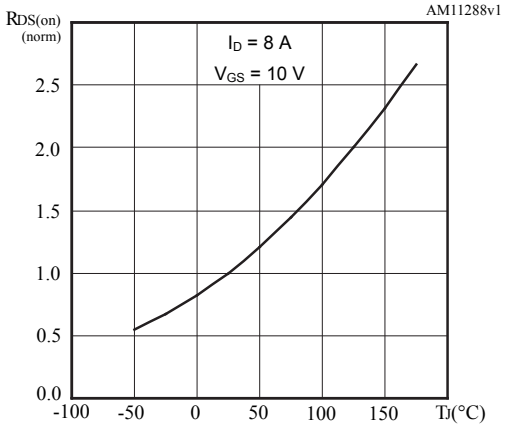
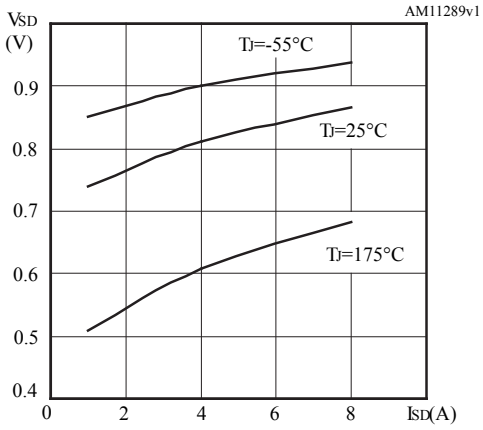
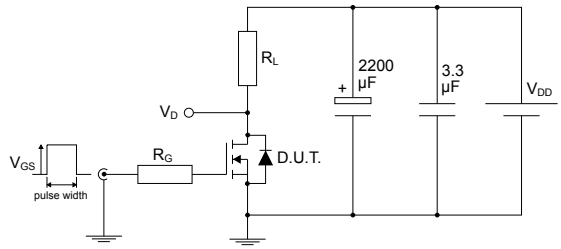


Figure 11. Source-drain diode forward characteristics



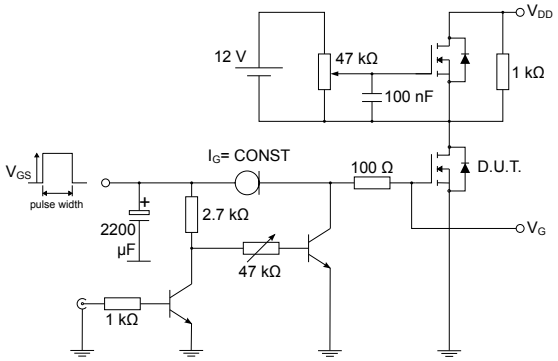
3 Test circuits

Figure 12. Test circuit for resistive load switching times



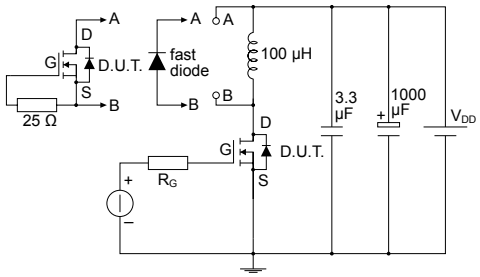
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Figure 13. Test circuit for gate charge behavior



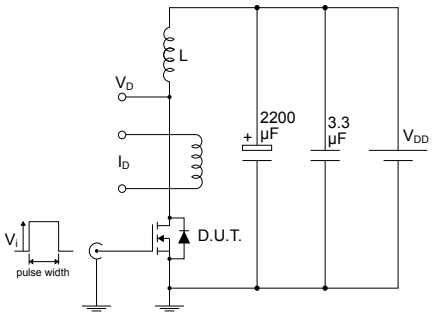
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Figure 14. Test circuit for inductive load switching and diode recovery times



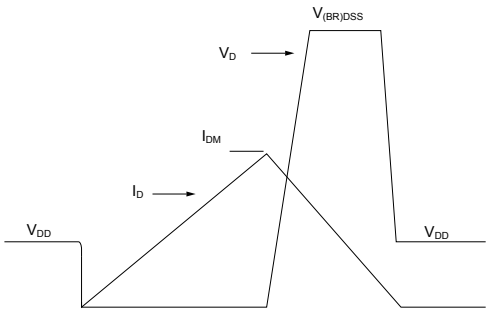
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Figure 15. Unclamped inductive load test circuit



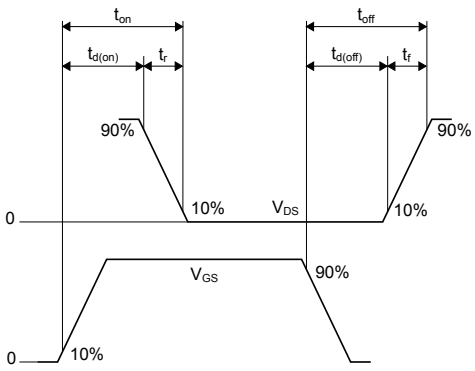
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Figure 16. Unclamped inductive waveform



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Figure 17. Switching time waveform



AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 18. DPAK (TO-252) type A2 package outline

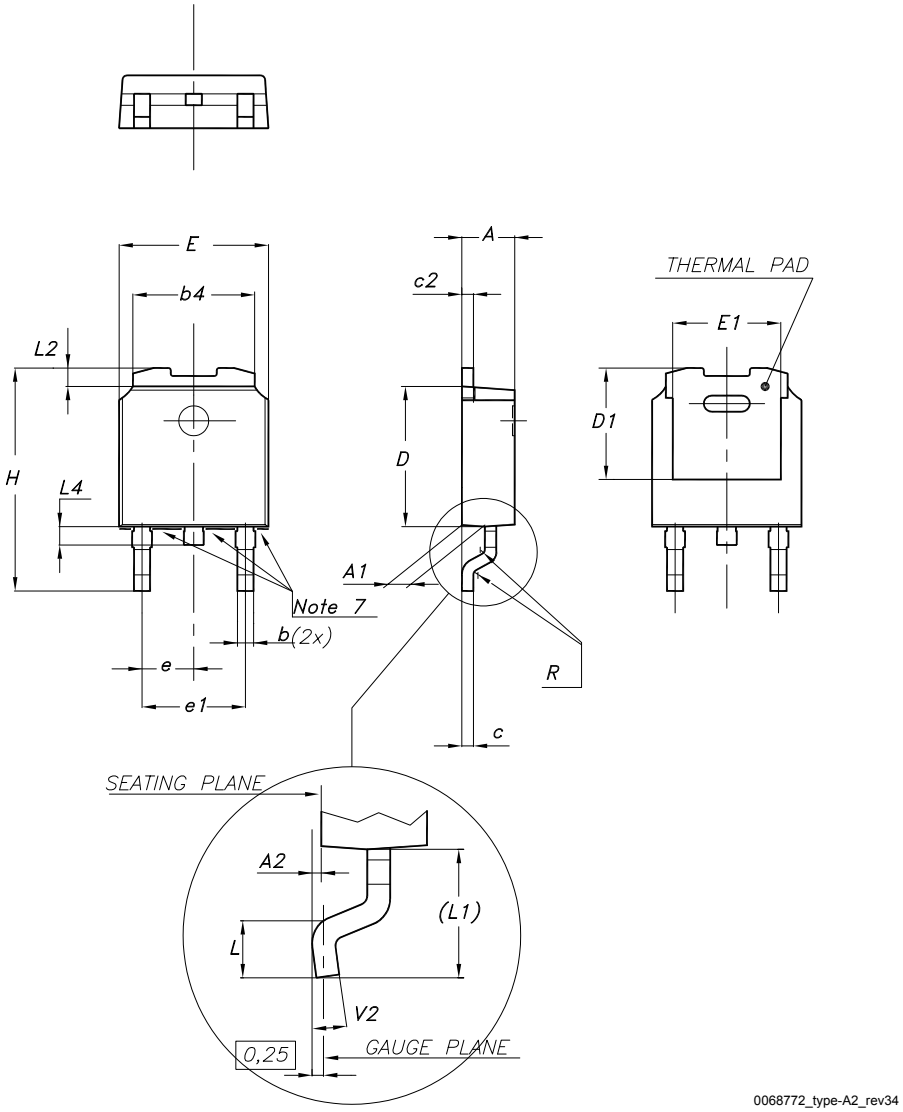
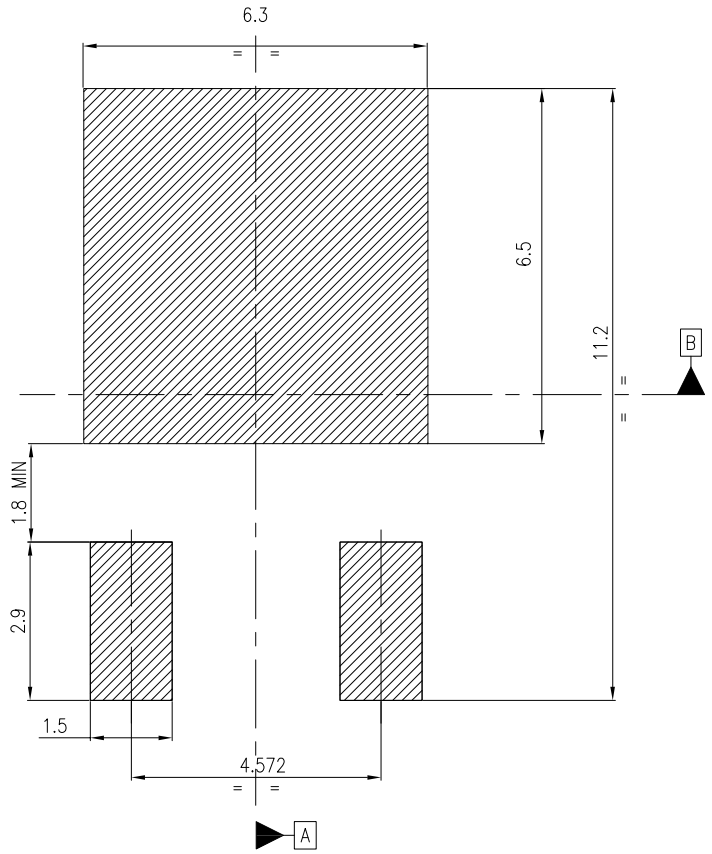


Table 8. **DPAK (TO-252) type A2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 19. DPAK (TO-252) recommended footprint (dimensions are in mm)



Notes:

1) This footprint is able to ensure insulation up to 630 Vrms (according to CEI IEC 664−1)

2) The device must be positioned within ⌖ 0.05 A B

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4.2 DPAK (TO-252) packing information

Figure 20. **DPAK (TO-252) tape outline**

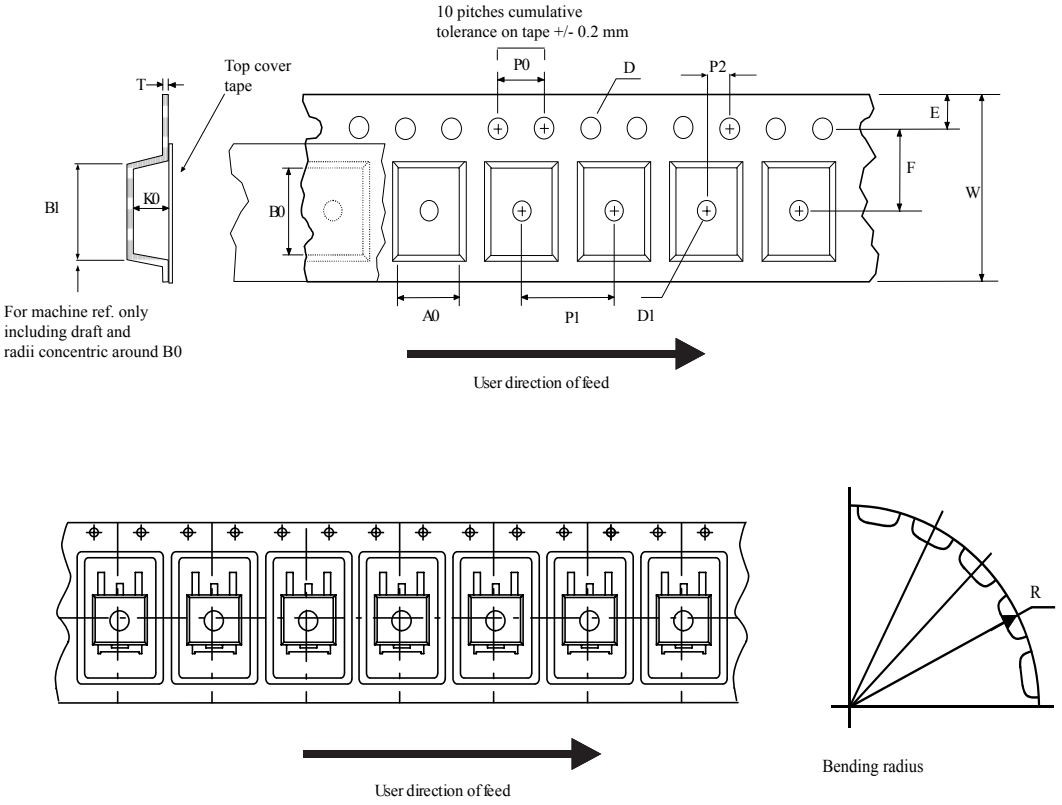
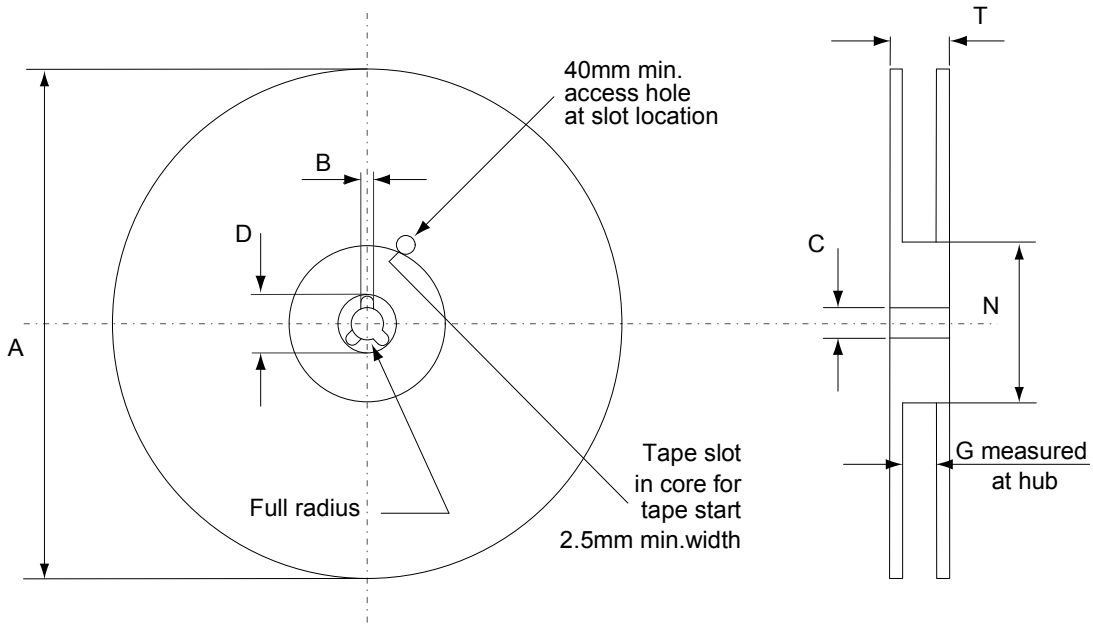


Figure 21. **DPAK (TO-252) reel outline**



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Table 9. **DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Revision history

Table 10. **Document revision history**

Date	Version	Changes
26-Apr-2012	1	First release.
03-Jul-2018	2	Removed maturity status indication from cover page. Updated title, features and description on cover page. Updated *Section 4.1 DPAK (TO-252) type A2 package information.* Minor text changes
09-Oct-2023	3	Updated title on cover page. Updated Section 4.1 DPAK (TO-252) type A2 package information. Minor text changes.

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